Description

The SI7216DN-T1-E3 uses advanced trench technology

to provide excellent R_{DS(ON)}, low gate charge and

operation with gate voltages as low as 4.5V. This

device is suitable for use as a

Battery protection or in other Switching application.

General Features

V_{DS} = 40V I_D =20 A

 $R_{DS(ON)}$ < 20m Ω @ V_{GS} =10V

Application

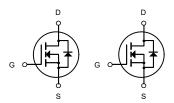
Battery protection

Load switch

Uninterruptible power supply



DFN3X3-8L



Dual N-Channel MOSFET

Package Marking and Ordering Information

Product ID	Pack	Brand	Qty(PCS)
SI7216DN-T1-E3	DFN3X3-8L	HXY MOSFET	5000

Absolute Maximum Ratings (T_C=25°Cunless otherwise noted)

Symbol	Parameter	Rating	Units
VDS	Drain-Source Voltage	40	V
VGS	Gate-Source Voltage	±20	V
I _D @T _C =25℃	Continuous Drain Current, V _{GS} @ 10V ¹	20	А
I _D @T _C =100°C	Continuous Drain Current, V _{GS} @ 10V ¹	13	А
IDM	Pulsed Drain Current ²	80	А
EAS	Single Pulse Avalanche Energy ³	31	mJ
IAS	Avalanche Current	60	А
P _D @T _A =25℃	Total Power Dissipation⁴	3	W
TSTG	Storage Temperature Range	-55 to 150	$^{\circ}$
TJ	Operating Junction Temperature Range	-55 to 150	$^{\circ}$
R _θ JA	Thermal Resistance Junction-Ambient ¹	40	°C/W

Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	40			V
∆BV _{DSS} /∆T _J	BVDSS Temperature Coefficient	Reference to 25°C , I _D =1mA		0.032		V/°C
Б	Static Drain-Source On-Resistance ²	V _{GS} =10V , I _D =7A		16	20	mΩ
Rds(on)		V _{GS} =4.5V , I _D =6A		20	26	
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =250uA	1.2	1.6	2.5	>
$\triangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	VGS-VDS , ID -230UA		-4.8		mV/°C
I _{DSS}	Drain-Source Leakage Current	V_{DS} =32V , V_{GS} =0V , T_J =25 $^{\circ}$ C			1	- uA
IDSS		V_{DS} =32V , V_{GS} =0V , T_{J} =55 $^{\circ}$ C			5	
Igss	Gate-Source Leakage Current	$V_{GS}=\pm 20V$, $V_{DS}=0V$			±100	nA
gfs	Forward Transconductance	V _{DS} =5V , I _D =7A		32		S
Rg	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		2.1		Ω
Qg	Total Gate Charge (4.5V)	V _{DS} =32V , V _{GS} =4.5V , I _D =7A		9.8		
Qgs	Gate-Source Charge			2.8		nC
Q_{gd}	Gate-Drain Charge			3.9		
T _{d(on)}	Turn-On Delay Time	V_{DD} =20V , V_{GS} =10V , R_{G} =3.3 Ω		2.8		ns
Tr	Rise Time			40.4		
T _{d(off)}	Turn-Off Delay Time			22.8		
T _f	Fall Time			6.4		
Ciss	Input Capacitance			1013		
Coss	Output Capacitance	V _{DS} =15V , V _{GS} =0V , f=1MHz		107		pF
Crss	Reverse Transfer Capacitance			76		
ls	Continuous Source Current ^{1,5}	V _G =V _D =0V , Force Current			20	Α
Isм	Pulsed Source Current ^{2,5}	vG-vD-0v , Force Current			85	Α
V _{SD}	Diode Forward Voltage ²	V_{GS} =0V , I_{S} =1A , T_{J} =25 $^{\circ}$ C			1	V
t _{rr}	Reverse Recovery Time	IF=7A , dI/dt=100A/μs ,		10		nS
Qrr	Reverse Recovery Charge	T _J =25°C		3.3		nC

Note:

^{1.} The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.

^{2.}The data tested by pulsed , pulse width $\,\leq\,300\text{us}$, duty cycle $\,\leq\,2\%$

^{3.} The EAS data shows Max. rating . The test condition is V_{DD} =25V, V_{GS} =10V,L=0.1mH, I_{AS} =25A

^{4.}The power dissipation is limited by 150°C junction temperature

^{5.} The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.



Typical Characteristics

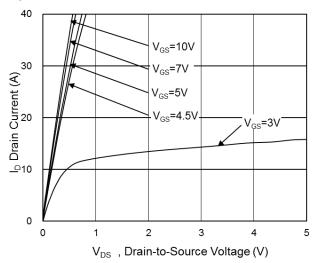


Fig.1 Typical Output Characteristics

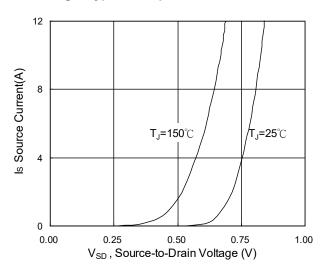


Fig.3 Forward Characteristics of Reverse

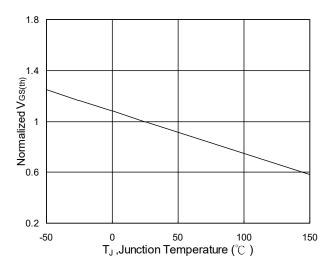


Fig.5 Normalized V_{GS(th)} vs. T_J

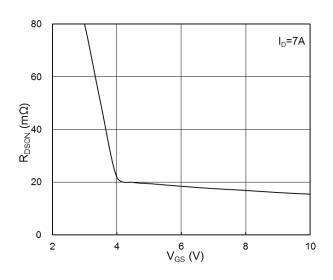


Fig.2 On-Resistance vs. G-S Voltage

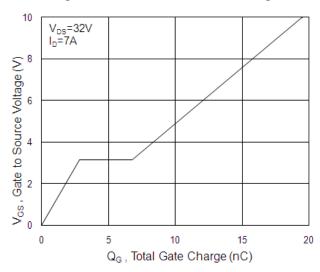


Fig.4 Gate-Charge Characteristics

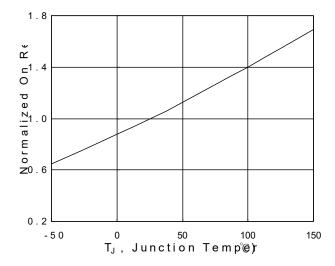
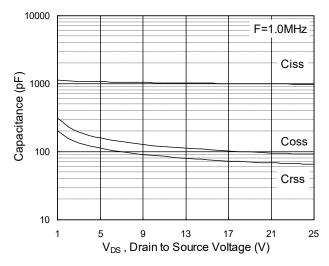


Fig.6 Normalized R_{DSON} vs. T_J





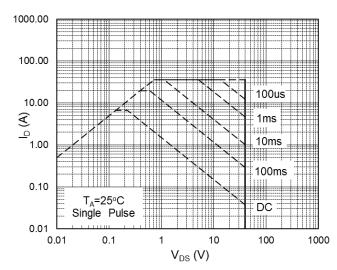


Fig.7 Capacitance

Fig.8 Safe Operating Area

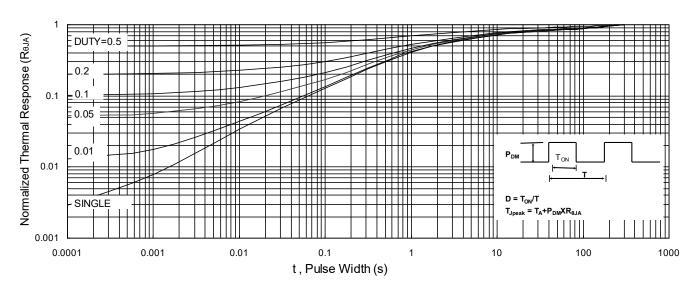


Fig.9 Normalized Maximum Transient Thermal Impedance

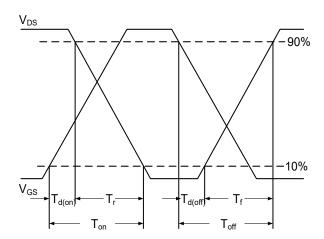


Fig.10 Switching Time Waveform

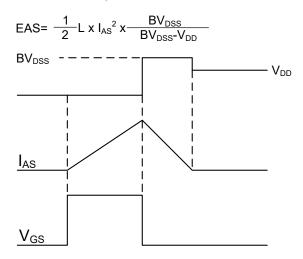
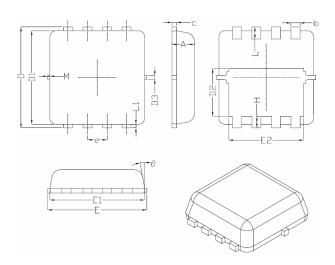


Fig.11 Unclamped Inductive Switching Waveform

DFN3X3-8L Package Information



Comphal	Dimensions In Millimeters			
Symbol	Min.	Nom.	Max.	
A	0.70	0.75	0.80	
b	0.25	0.30	0.35	
С	0.10	0.15	0.25	
D	3.25	3.35	3.45	
D1	3.00	3.10	3.20	
D2	1.48	1.58	1.68	
D3	-	0.13	-	
E	3.20	3.30	3.40	
E1	3.00	3.15	3.20	
E2	2.39	2.49	2.59	
е	0.65BSC			
Н	0.30	0.39	0.50	
L	0.30	0.40	0.50	
L1	-	0.13	-	
M	*	*	0.15	
θ		10 [°]	12 [°]	

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